1.	TITLE OF THE INVENTION
2.	NAMES OF THE INVENTORS
3.	RESUBMISSION RESPONSES: THIS SECTION TO BE LEFT BLANK FOR INITIAL SUBMISSIONS FOR USE IN RESUBMISSIONS ONLY.
	esponse: Paste the review comments below and respond to each of them. If other ons of the document are also updated, include a short summary of the changes here.
4.	TECHNOLOGY BACKGROUND
4.1 Pr	roblem Definition – What technical problem did you solve?
4.2 Pr	revious Solution (if any):
	A. Describe any previous solution used to solve the problem
5.	OVERVIEW OF THE INVENTION

5.1 Short Summary – In 1-3 sentences, describe the core of your solution 5.2 Advantages – In 1-3 sentences, describe the value of the invention to Intel or to our customers. 6. **DETECTABILITY** 6.1 Please describe in detail how your invention is detectable in a final product. A. If your invention results in a specific structural feature please describe the appearance of that feature (e.g., include SEM/TEMs of actual features if available). B. If there are visual inspection and/or reverse engineering techniques that can be used to identify the feature, please describe them. C. If documentation such as product literature would show usage of the invention, please let us know what to look for in that regard.

INVENTION DISCLOSURE FORM (IDF)

7. DETAILS OF THE INVENTION

INVENTION DISCLOSURE FORM (IDF)

7.1 Provide details that help us fully understand your invention, including details on how you solved the technical problem, and at least one figure. You may also provide flowcharts, graphs, slides, or data to support your description. Where appropriate, please provide and explain any empirical support, such as experimental data or simulation results, that can demonstrate the viability of your invention.